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TITLE: 516 THERMALLY ENHANCED PBGA, WITH HEAT SPREADER, 27 x 27 PKG, 1MM PITCH	DOCUMENT NO: 98ASA10789D	REV: 0	
	CASE NUMBER: 1946-01	21 FEB 2007	
	STANDARD: JEDEC MS-034		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PACKAGE CODE 5368 IS TO ACCOUNT FOR PGE AND THE BUILT-IN HEAT SPREADER.

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